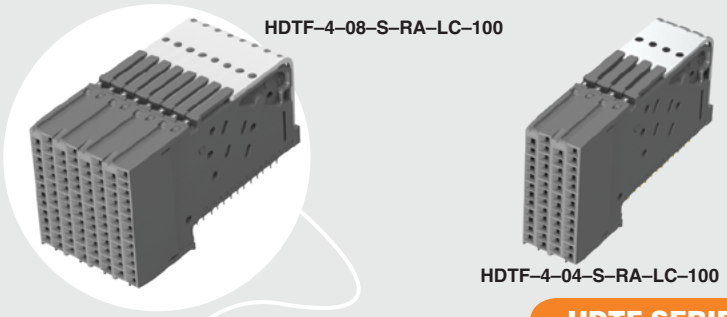
samtec

XCede HD



(1.80 mm) .071"

HDTF SERIES

XCede® HD BACKPLANE RECEPTACLE

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HDTF

Insulator Material:
Liquid Crystal Polymer
Contact Material:
Copper Alloy
Plating:
Sn or Au over
50 µ" (1.27 µm) Ni
Operating Temp Range:
-40 °C to +105 °C
Current Rating:
Testing Now!
RoHS Compliant:
Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality

FILE NO. E111594

TOOLING

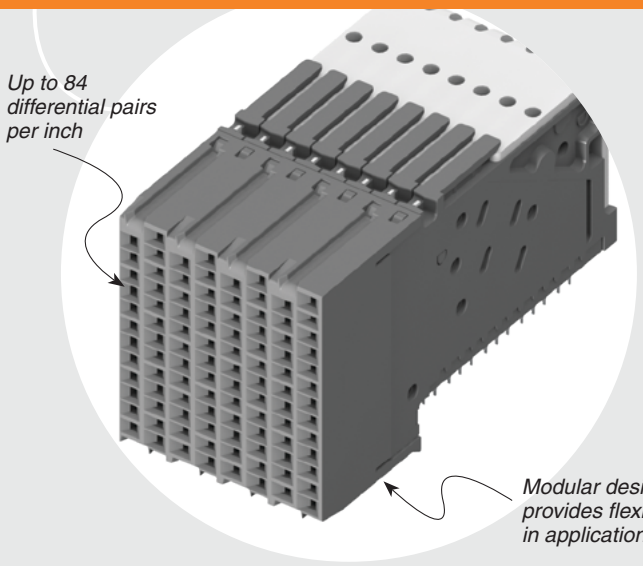
- For press-fit extraction and insertion tool options, visit www.samtec.com/tooling

Mates with:
HDTM

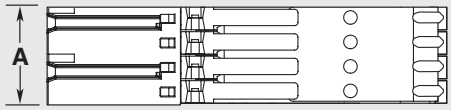
ALSO AVAILABLE
(Customer Defined Configurations)

Power and keying/guidance modules also are available but require a single customizable BSP product. A BSP product is built by combining any number, in any configuration, of HDTFs, power and keying/guidance modules to create one receptacle.

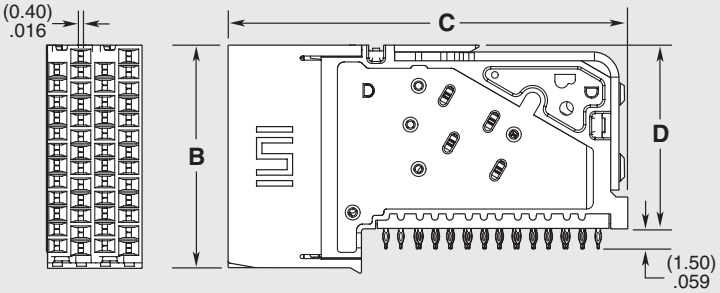
Contact HSBP@samtec.com for more information about building a BSP product.



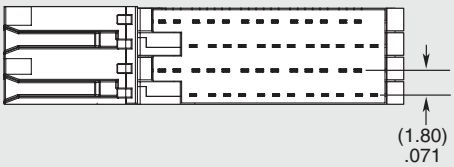
HDTF	PAIRS PER COLUMN	NO. OF COLUMNS	PLATING	RA	WAFERS	IMPEDANCE
	–3, –4, –6 = Pairs Per Column	–04 = Four Columns –06 = Six Columns –08 = Eight Columns	–S = 30 µ" (0.76 µm) Gold in contact area, Matte Tin on tail		–LC = Standard –HS = High-Speed	–100 = 100 Ω –085 = 85 Ω



NO. OF COLUMNS	A
–04	(7.2) .28
–06	(10.8) .42
–08	(14.4) .57



PAIRS PER COLUMNS	B	C	D
–3	(12.8) .50	(26.0) 1.02	(9.80) .386
–4	(16.4) .64	(29.4) 1.16	(13.5) .53
–6	(23.6) .93	(36.6) 1.44	(20.7) .81



Note:
XCede® is a registered trademark of Amphenol.